

# INTERNATIONAL STANDARD

Printed board assemblies –  
Part 4: Sectional specification – Requirements for terminal soldered assemblies  
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IEC 61191-4:2017

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INTERNATIONAL  
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**PRINTED BOARD ASSEMBLIES –****Part 4: Sectional specification –  
Requirements for terminal soldered assemblies**

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International Standard IEC 61191-4 has been prepared by IEC technical committee 91: Electronics assembly technology.

This second edition cancels and replaces the first edition published in 1998. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- The requirements have been updated to be compliant with the acceptance criteria in IPC-A-610F.

The text of this International Standard is based on the following documents:

CDV	Report on voting
91/1399/CDV	91/1434/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61191 series, published under the general title *Printed board assemblies*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

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## PRINTED BOARD ASSEMBLIES –

### Part 4: Sectional specification – Requirements for terminal soldered assemblies

#### 1 Scope

This part of IEC 61191 prescribes requirements for terminal soldered assemblies. The requirements pertain to those assemblies that are entirely terminal/wire interconnecting structures or to the terminal/wire portions of those assemblies that include other related technologies (i.e. surface mounting, through-hole mounting, chip mounting).

#### 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

IEC 61191-1:2013, *Printed board assemblies – Part 1: Generic specification – Requirements for soldered electrical and electronic assemblies using surface mount and related assembly technologies*

[IEC 61191-4:2017](https://standards.iteh.ai/catalog/standards/sist/0e3af427-cd15-4a2f-8a85-340596838ed1/iec-61191-4-2017)

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#### 3 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 60194 apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

#### 4 General requirements

Requirements of IEC 61191-1 are a mandatory part of this specification.

Workmanship shall meet the requirements of IPC-A-610 in accordance with the classification requirements of this document.

#### 5 General terminal and part mounting requirements

##### 5.1 General

The requirements of 5.2 are applicable to terminals and part mounting in all types of assemblies.



## 5.2 Wire and cable preparation

### 5.2.1 General

Sufficient insulation cover shall be stripped from the wire or leads to provide for insulation clearances as specified. Chemical stripping agents shall be used for solid wire only and shall be neutralized or removed prior to soldering. In stripping insulation, care should be taken to avoid nicking or otherwise damaging the wire or the remaining insulation. For level A or B assemblies, the number of nicked or broken strands in a single wire shall not exceed the limits given in Table 1. For wires used at a potential of 6 kV or greater, or for level C assemblies, there shall be no broken strands. The number of nicked strands shall be in accordance with Table 1. Insulation discolouration resulting from thermal stripping is permissible.

**Table 1 – Nicked or broken strand limits**

Number of strands	Maximum allowable scraped, nicked or broken strands		
	Level A and B	Level C not tinned	Level C pretinned
1 (solid)	No damage in excess of 10 % conductor diameter		
2 to 6	0	0	0
7 to 15	1	0	1
16 to 25	3	0	2
26 to 40	4	3	3
41 to 60	5	4	4
61 to 120	6	5	5
121 or more	6 % of strands	5 % of strands	5 % of strands

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### 5.2.2 Tinning of stranded wire

Portions of stranded wire to be soldered shall be tinned prior to mounting. The solder shall wet the stranded wire and penetrate to the inner strands of the wire. Wicking of solder under the insulation shall be minimized.

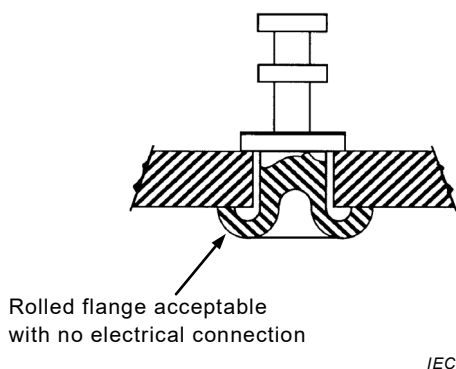
## 5.3 Terminal installation

### 5.3.1 General

The detailed requirements for installation of solder terminals are defined in 5.3.2 to 5.3.8.

### 5.3.2 Terminal mounting (mechanical)

Terminals not connected to printed wiring or ground planes shall be of the rolled flange configuration (see Figure 1). A printed foil land may be used as a seating surface for a rolled flange provided that the land is isolated and not connected to active printed wiring or ground plane.



**Figure 1 – Rolled flange terminal**

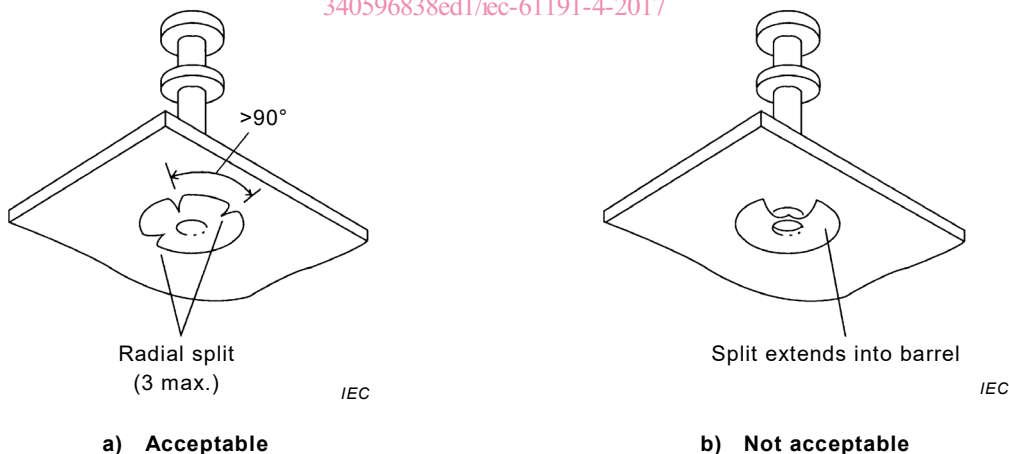
**5.3.3 Terminal shank discontinuities**

The shank of the terminal shall not be perforated, split, cracked, and there shall not be discontinuity to the extent that oils, flux, inks, or other substances used for processing the printed board can be entrapped. Circumferential cracks or splits in the shank are not acceptable regardless of the extent.

**5.3.4 Flange discontinuities**

The rolled flange shall not be split, cracked or otherwise discontinuous to the extent that flux, oils, inks, or other liquid substances used for processing the printed board can be entrapped within the mounting hole. After rolling, the rolled area shall be free of circumferential splits or cracks, but may have a maximum of three radial splits or cracks provided that the splits or cracks are separated by at least 90° and do not extend into the barrel of the terminal (see Figure 2).

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**Figure 2 – Rolled flange discontinuities**

**5.3.5 Terminal mounting (electrical)**

Flared flange terminals shall be mounted in non-interfacial plated through-holes provided the mounting is in conjunction with a land or ground plane on the flared side as shown in Figure 3a. They shall not be flared to the base material of the printed board. Funnel shoulder terminals shall not be used (see Figure 3b). Terminals may be mounted in non-plated through-holes with active circuitry on the top-side (or primary side) and a rolled flange on the backside of the board (see Figure 3c).

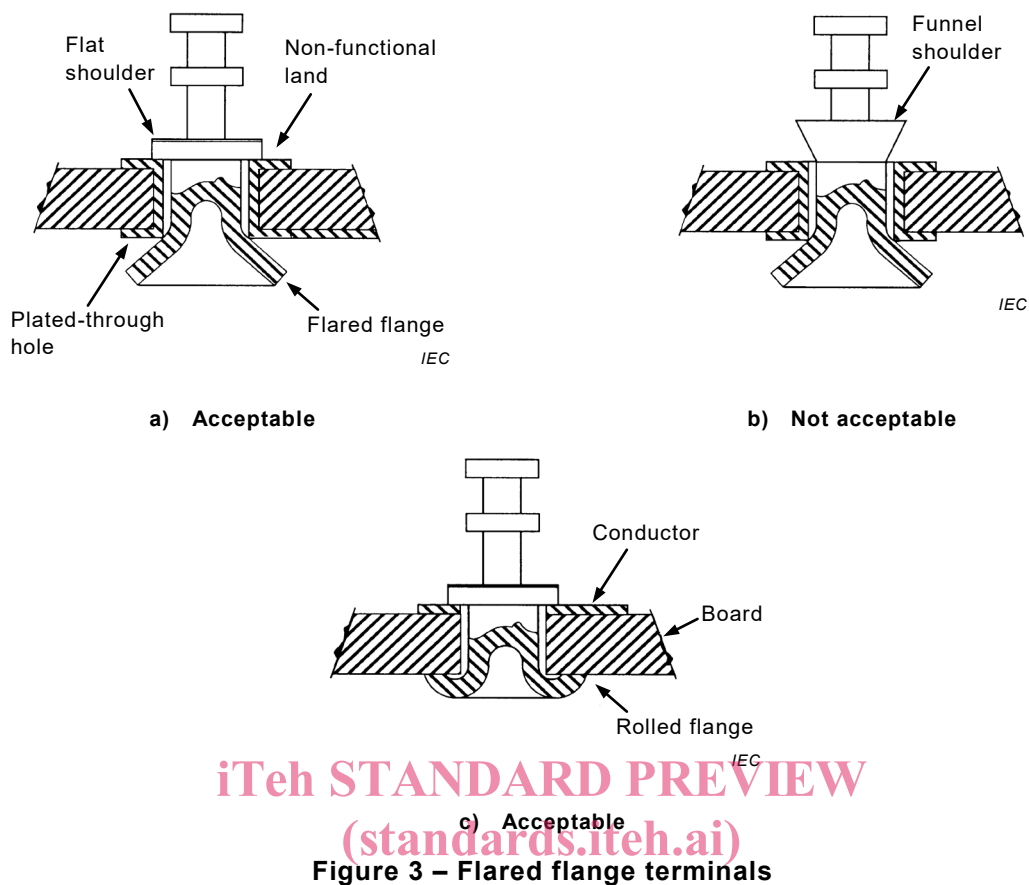


Figure 3 – Flared flange terminals

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### 5.3.6 Flange angles

Flared flanges shall be formed to include an angle of between  $35^\circ$  and  $120^\circ$  and shall extend between 0,4 mm and 1,5 mm beyond the surface of the land provided minimum electrical spacing requirements are maintained (see Figure 4), and the flare diameter does not exceed the diameter of the land.

*Dimensions in millimetres*

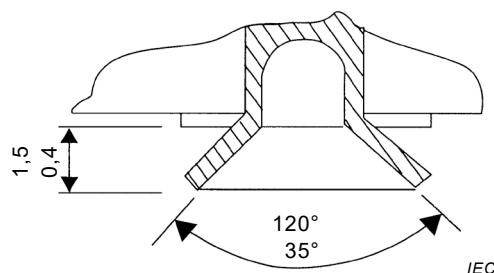


Figure 4 – Flared angles

### 5.3.7 Shank discontinuities

After installation, the shank of the terminal shall meet the requirements of 5.3.3.

### 5.3.8 Flared flange discontinuities

The flared flange of a terminal shall not be perforated, split, cracked, or otherwise discontinuous to the extent that flux, oils, inks or other substances used for processing the printed board can be entrapped. After flaring, the flange shall conform to 5.3.4.